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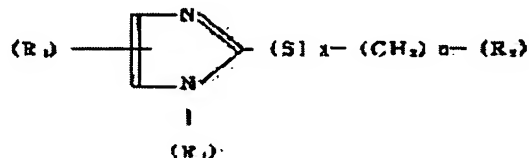
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(54) TREATMENT OF METALLIC SURFACE SUCH AS SOLDER, ELECTROLESS SOLDER, AG, NI, ZN, CU AND CU ALLOY

(57)Abstract:

PURPOSE: To form a chemical conversion film superior in moisture resistance, chemical resistance and heat resistance on a metallic surface, to prevent rust and to enhance a soldering property and a wetting property by bringing the metallic surface into contact with an aqueous solution of a specific imidazole derivative.

CONSTITUTION: A metallic surface such as solder, electroless solder, Ag, Ni, Zn, Cu, and Cu alloy is brought into contact with an aqueous solution incorporating a compound represented with a formula, (in the formula, R1: hydrogen, alkyl group, phenylalkyl group, and alkyl group, R2: alkyl group, and phenylalkyl group, R3: hydrogen, sulfo group, alkyl group, phenyl group, and halogen atom, n=0 to 17, and x=0 to 1) or a salt of its derivative. The aqueous solution incorporates about 0.1-5% the above described



compound and further the solution containing an organic acid, an inorganic acid and a metallic compound is preferred and moreover an ammonia salt or the like is added, if necessary. A printed wiring board with reliability is produced by performing a solder reflow treatment, a soldering treatment, and an alkaline solution treatment, etc., after the above described surface treatment.

LEGAL STATUS

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